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PATENT APPLICATION
DOCKET NO. M085

*entered
W/RCE
1/21/05
T. Young
1/28/05*

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10 IN THE
11 UNITED STATES PATENT AND TRADEMARK OFFICE

12 GROUP ART UNIT: 2811

13 EXAMINER: Parekh, Nitin

14 INVENTOR(S): Alter, M.

15 SERIAL NO.: 10/648,016

16 CONF. NO.: 3466

17
18 FILED: 08/26/2003

19 SUBJECT: Semiconductor Devices Integrated with Wafer-Level Packaging

20 REPLY TO OFFICE ACTION AND REQUEST FOR RECONSIDERATION
21 UNDER 37 CFR 1.116

22 TO: COMMISSIONER FOR PATENTS
23 POB 1450
24 ALEXANDRIA, VA 22313

25 SIR:

26 In accordance with the notice "REVISED AMENDMENT PRACTICE: 37 CFR 1.121 CHANGED,
27 effective July 30, 2003, the MPEP and 37 CFR, following are:

- 28 (A) INTRODUCTORY COMMENTS,
29 (B) AMENDMENTS TO THE SPECIFICATION,
30 (C) AMENDMENTS TO THE CLAIMS,
31 (D) REMARKS, including DRAWING AMENDMENTS, if any.

S/N: 10/648016
Applicant Docket No.: M085
Reply to Final